

WHAT IS CLAIMED IS:

1. An electronic-circuit unit comprising:

an alumina board;

circuit elements comprising a capacitor, a resistor, and an inductive device, are formed as thin films on the alumina board;

an electrically conductive pattern connected to at least one circuit element is formed as a thin film on the alumina board;

a semiconductor bare chip is mounted on the alumina board; and

an end-face electrode connected to the electrically conductive pattern is formed on a side face of the alumina board,

wherein the semiconductor bare chip is wire-bonded to the electrically conductive pattern.

2. An electronic-circuit unit according to Claim 1, wherein a Cu layer is formed on a surface of the capacitor and the inductive device.

3. An electronic-circuit unit according to Claim 1, wherein the end-face electrode is formed as a thick film by the use of a low-temperature baked material.

4. An electronic-circuit unit according to Claim 3,

wherein an Au plating layer is formed on the end-face electrode.

5. An electronic-circuit unit according to Claim 3, wherein the end-face electrode is formed as a thick film only at each of two sides along opposing edges of the alumina board.

6. An electronic-circuit unit according to Claim 4, wherein the end-face electrode is formed as a thick film only at each of two sides along opposing edges of the alumina board.

7. An electronic-circuit unit comprising:  
circuit element comprising a capacitor, a resistor, and an inductive device, formed as thin films on an alumina board having a rectangular, plane shape;

a semiconductor bare chip wire-bonded on the alumina board;

grounding electrodes formed at the ends of two sides along opposing edges of the alumina board; and

an input electrode and an output electrode formed away from the ends.

8. An electronic-circuit unit according to Claim 7, wherein a shielding cover is mounted to the alumina board so as to cover the circuit elements and the

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